

Product/process change notification

PCN N° 2022-094-A

Dear customer,

Please find attached our Infineon Technologies AG PCN:

Introduction of an additional assembly site at Infineon Technologies Co., Ltd., Wuxi, China for CIPOS™ mini products

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **2023-03-30**
- Infineon aligns with the widely recognized JEDEC STANDARD “**JESD46**“, which stipulates: **“Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change.”**

Your prompt reply will help Infineon to assure a smooth and well-executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG

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Product/process change notification

PCN N° 2022-094-A

► **Products affected**

Please refer to attached affected product list
 “pcn_2022-094-A_[customer-no].pdf”

► **Detailed change information**

Subject Introduction of an additional assembly location at Infineon Technologies Co., Ltd., Wuxi, China for CIPOS™mini products

Reason Expansion of assembly production to assure continuity of supply and enable flexible manufacturing.

Description	<u>Old</u>	<u>New</u>
Assembly location	<ul style="list-style-type: none"> ■ Infineon Technologies Power Semitech Co., Ltd., Cheonan-Si, Korea 	<ul style="list-style-type: none"> ■ Infineon Technologies Power Semitech Co., Ltd., Cheonan-Si, Korea and Infineon Semiconductors (Wuxi) Co. Ltd., Wuxi, China

► **Product identification**

No change in SP ordering number, traceability assured via lot code.

► **Impact of change**

No impact on electrical performance. Quality and reliability verified by qualification. There is no change in form, fit and function.

► **Attachments**

“pcn_2022-094-A_[customer-no].pdf” affected product list
 2_cip22094_a Qualification report

► **Time schedule**

- Final qualification report available
- First samples available Major types available, others on request
- Intended start of delivery 2023-08-01, existing stock will be consumed first.

If you have any questions, please do not hesitate to contact your local sales office.

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Introduction of an additional assembly site at Infineon Technologies Co., Ltd., Wuxi, China
for CIPOS(TM)mini products



Affected products sold to DIGI-KEY (4002348)

Sales name	SP number	OPN	Package	Customer part number
IGCM04F60GA	SP001246994	IGCM04F60GAXKMA1	PG-MDIP-24-12	IGCM04F60GAXKMA1
IGCM06F60GA	SP001247004	IGCM06F60GAXKMA1	PG-MDIP-24-12	IGCM06F60GAXKMA1
IGCM10F60GA	SP001247016	IGCM10F60GAXKMA1	PG-MDIP-24-12	IGCM10F60GAXKMA1
IGCM15F60GA	SP001247022	IGCM15F60GAXKMA1	PG-MDIP-24-12	IGCM15F60GAXKMA1
IGCM20F60GA	SP001247028	IGCM20F60GAXKMA1	PG-MDIP-24-12	IGCM20F60GAXKMA1
IKCM10H60GA	SP001247198	IKCM10H60GAXKMA1	PG-MDIP-24-12	IKCM10H60GAXKMA1
IKCM10L60GA	SP001370916	IKCM10L60GAXKMA1	PG-MDIP-24-12	IKCM10L60GAXKMA1
IKCM15H60GA	SP001247204	IKCM15H60GAXKMA2	PG-MDIP-24-12	IKCM15H60GAXKMA2
IKCM15L60GA	SP001247208	IKCM15L60GAXKMA1	PG-MDIP-24-12	IKCM15L60GAXKMA1
IKCM20L60GA	SP001247214	IKCM20L60GAXKMA1	PG-MDIP-24-12	IKCM20L60GAXKMA1
IKCM30F60GA	SP001247216	IKCM30F60GAXKMA1	PG-MDIP-24-12	IKCM30F60GAXKMA1

Qualification Test Report



PCN No: PCN-2022-094-A

Date: 2023-02-01

Title: Introduction of an additional assembly site at Infineon Technologies Co., Ltd., Wuxi, China for CIPOS™ mini products

Reason for choosing the following test vehicles:

IGCM04G60HA Smallest chip size and lowest current rating

IKCM15L60GA Medium chip size and medium current rating

IKCM30F60GA Biggest chip size and highest current rating

Scope of qualification: All CIPOS™ MiniFP_2nd site enabling in Wuxi

Assessment of Q-Results: Passed all reliability qualification items

Stress test	Abbreviation	Test conditions	Readout	IGCM04G60HA (Lot1:VE209591C03)	IKCM15L60GA (Lot2: PF219602C06)	IKCM30F60GA (Lot3: PF216822C07)
High Temperature Storage Life JESD22-A103	HTSL	Ta = 125°C	168 h	0 / 22	0 / 22	0 / 22
			500 h	0 / 22	0 / 22	0 / 22
			1000 h	0 / 22	0 / 22	0 / 22
Temperature Cycling JESD22-A104	TC	Ta = -40°C ~ 125°C	200 x	0 / 22	0 / 22	0 / 22
			500 x	0 / 22	0 / 22	0 / 22
			1000 x	0 / 22	0 / 22	0 / 22
High Accelerated Stress test (unbiased) JESD22-A118	uHAST	Ta = 130°C RH = 85%	96 h	0 / 22	0 / 22	0 / 22
Temperature Humidity Bias JESD22-A101	THB	Ta = 85°C RH = 85% VCE = 80 V VDD = 15.0 V VBS = 15.0 V	168 h	0 / 22	0 / 22	0 / 22
			500 h	0 / 22	0 / 22	0 / 22
			1000 h	0 / 22	0 / 22	0 / 22
Intermittent Operational Life MIL-STD-750 Method 1037	IOL	Delta Tj = 100 °C	2500 x	0 / 12	0 / 12	0 / 12
			5000 x	0 / 12	0 / 12	0 / 12
			10000 x	0 / 12	0 / 12	0 / 12
Resistance to solder heat JESD22-B106	RSH	270°C +/-5°C 7 +/-0s dip	After	0 / 22	0 / 22	0 / 22
Solder-ability JESD22-B102	Solder-ability	Precond: Dry bake, Solder temp/immersion time: 245°C, 5sec, Dip&Look	After	0 / 5	0 / 5	0 / 5
ESD Characterization - HBM ANSI/ESDA/JEDEC JS-001-2017	ESD HBM	Pulse interval = 0.3-10sec Discharge option = Yes Polarity = +/-	2000V	0 / 9	0 / 9	0 / 9
ESD Characterization - CDM ANSI/ESDA/JEDEC JS-002-2018	ESD CDM	3x pulses	500V	0 / 3	0 / 3	0 / 3